ABSTRACT

INTEGRATED CIRCUIT SYSTEM WITH CARBON ENHANCEMENT

An integrated circuit hard mask processing system is provided including providing a substrate having an integrated circuit; forming an interconnect layer over the integrated circuit; applying a low-K dielectric layer over the interconnect layer; forming a via opening through the low-K dielectric layer to the interconnect layer; and forming a carbon implant region around the via opening, a trench opening, or a combination thereof, for protecting the low-K dielectric layer.

FIG 1